

Fan-Out Packaging Market Report: Trends, Forecast and Competitive Analysis

<https://marketpublishers.com/r/FDD8E78C506DEN.html>

Date: May 2024

Pages: 150

Price: US\$ 4,850.00 (Single User License)

ID: FDD8E78C506DEN

Abstracts

Get it in 2 to 4 weeks by ordering today

The future of the fan-out packaging market looks promising with opportunities in the outsourced semiconductor assembly and testing (OSAT), foundry, and integrated device manufacturer (IDM) markets. The global fan-out packaging market is expected to decline in 2020 due to the global economic recession led by the COVID-19 pandemic. However, the market will witness recovery in the year 2021, and it is expected to grow with a CAGR of 18% to 21% from 2020 to 2025. The major drivers for this market are growing applications in footprint sensitive devices, such as smartphones, owing to requirement of high performing, energy efficient, thin, and small form factor packages.

A more than 150 page report is developed to help in your business decisions. Sample figures with some insights are shown below. To learn the scope of, benefits, companies researched and other details of fan-out packaging market report download the report brochure.

The study includes trends and forecasts for the global fan-out packaging market by type, carrier type, business model, and region as follows:

By Type [\$M shipment analysis for 2014 – 2025]:

Core Fan-Out

High-Density Fan-Out

By Carrier Type [\$M shipment analysis for 2014 – 2025]:

200 mm

300 mm

Panel

By Business Model [\$M shipment analysis for 2014 – 2025]:

OSAT

Foundary

IDM

By Region [\$M shipment analysis for 2014 – 2025]:

North America

United States

Canada

Mexico

Europe

Germany

United Kingdom

France

Italy

Asia Pacific

China

Japan

India

South Korea

The Rest of the World

Some of the fan-out packaging companies profiled in this report include Taiwan Semiconductor Manufacturing Company, Jianguo Changjiang Electronics, Amkor Technology, Samsung Electro-Mechanics, and Powertech Technology

Core fan-out and high density fan-out packaging are the two major types used in the OSAT, foundry and integrated device manufacturer (IDM) markets. Core fan-out packaging will remain the largest type segment over the forecast period.

Features of Fan-Out Packaging Market

Market Size Estimates: Fan-out packaging market size estimation in terms of value (\$M)

Trend and Forecast Analysis: Market trends (2014-2019) and forecast (2020-2025) by various segments and regions.

Segmentation Analysis: Market size by type, carrier type, and business model

Regional Analysis: Fan-out packaging market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

Growth Opportunities: Analysis on growth opportunities in different type, carrier type, business model, and regions for fan-out packaging market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the fan-out packaging market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

This report answers following 11 key questions

Q.1 What are some of the most promising potential, high-growth opportunities for the global fan-out packaging market by type (core fan-out and high-density fan-out), carrier type (200 mm, 300 mm, and panel), business model (OSAT, foundary, and IDM), and region (North America, Europe, Asia Pacific, and the Rest of the World)?

Q.2 Which segments will grow at a faster pace and why?

Q.3 Which regions will grow at a faster pace and why?

Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the fan-out packaging market?

Q.5 What are the business risks and threats to the fan-out packaging market?

Q.6 What are emerging trends in this fan-out packaging market and the reasons behind them?

Q.7 What are some changing demands of customers in the fan-out packaging market?

Q.8 What are the new developments in the fan-out packaging market? Which companies are leading these developments?

Q.9 Who are the major players in the fan-out packaging market? What strategic initiatives are being implemented by key players for business growth?

Q.10 What are some of the competitive products and processes in the fan-out packaging market, and how big of a threat do they pose for loss of market share via material or product substitution?

Q.11 What M&A activities did take place in the last five years in the fan-out packaging market?

Contents

1. EXECUTIVE SUMMARY

2. MARKET BACKGROUND AND CLASSIFICATIONS

2.1: Introduction, Background, and Classifications

2.2: Supply Chain

2.3: Industry Drivers and Challenges

3. MARKET TRENDS AND FORECAST ANALYSIS FROM 2014 T 2025

3.1: Macroeconomic Trends (2014-2019) and Forecast (2020-2025)

3.2: Global Fan-Out Packaging Market Trends (2014-2019) and Forecast (2020-2025)

3.3: Global Fan-Out Packaging Market by Type

3.3.1: Core Fan-Out

3.3.2: High-Density Fan-Out

3.4: Global Fan-Out Packaging Market by Carrier Type

3.4.1: 200 mm

3.4.2: 300 mm

3.4.3: Panel

3.5: Global Fan-Out Packaging Market by Business Model

3.5.1: OSAT

3.5.2: Foundary

3.5.3: IDM

4. MARKET TRENDS AND FORECAST ANALYSIS BY REGION FROM 2014 T 2025

4.1: Global Fan-Out Packaging Market by Region

4.2: North American Fan-Out Packaging Market

4.2.1: Market by Type

4.2.2: Market by Carrier Type

4.2.3: Market by Business Model

4.2.4: The US Fan-Out Packaging Market

4.2.5: The Canadian Fan-Out Packaging Market

4.2.6: The Mexican Fan-Out Packaging Market

4.3: European Fan-Out Packaging Market

4.3.1: Market by Type

4.3.2: Market by Carrier Type

- 4.3.3: Market by Business Model
- 4.3.4: German Fan-Out Packaging Market
- 4.3.5: United Kingdom Fan-Out Packaging Market
- 4.3.6: French Fan-Out Packaging Market
- 4.3.7: Italian Fan-Out Packaging Market
- 4.4: APAC Fan-Out Packaging Market
 - 4.4.1: Market by Type
 - 4.4.2: Market by Carrier Type
 - 4.4.3: Market by Business Model
 - 4.4.4: Chinese Fan-Out Packaging Market
 - 4.4.5: Japanese Fan-Out Packaging Market
 - 4.4.6: Indian Fan-Out Packaging Market
 - 4.4.7: South Korean Fan-Out Packaging Market
- 4.5: ROW Fan-Out Packaging Market
 - 4.5.1: Market by Type
 - 4.5.2: Market by Carrier Type
 - 4.5.3: Market by Business Model

5. COMPETITOR ANALYSIS

- 5.1: Product Portfolio Analysis
- 5.2: Geographical Reach
- 5.3: Porter's Five Forces Analysis

6. GROWTH OPPORTUNITIES AND STRATEGIC ANALYSIS

- 6.1: Growth Opportunity Analysis
 - 6.1.1: Growth Opportunities for the Global Fan-Out Packaging Market by Type
 - 6.1.2: Growth Opportunities for the Global Fan-Out Packaging Market by Carrier Type
 - 6.1.3: Growth Opportunities for the Global Fan-Out Packaging Market by Business Model
 - 6.1.4: Growth Opportunities for the Global Fan-Out Packaging Market by Region
- 6.2: Emerging Trends in the Global Fan-Out Packaging Market
- 6.3: Strategic Analysis
 - 6.3.1: New Product Development
 - 6.3.2: Capacity Expansion of the Global Fan-Out Packaging Market
 - 6.3.3: Technology Development
 - 6.3.4: Mergers and Acquisitions in the Global Fan-Out Packaging Industry

7. COMPANY PROFILES OF LEADING PLAYERS

7.1: Taiwan Semiconductor Manufacturing Company

7.2: Jiangsu Changjiang Electronics

7.3: Amkor Technology

7.4: Samsung Electro-Mechanics

7.5: Powertech Technology

I would like to order

Product name: Fan-Out Packaging Market Report: Trends, Forecast and Competitive Analysis

Product link: <https://marketpublishers.com/r/FDD8E78C506DEN.html>

Price: US\$ 4,850.00 (Single User License / Electronic Delivery)

If you want to order Corporate License or Hard Copy, please, contact our Customer Service:

info@marketpublishers.com

Payment

To pay by Credit Card (Visa, MasterCard, American Express, PayPal), please, click button on product page <https://marketpublishers.com/r/FDD8E78C506DEN.html>

To pay by Wire Transfer, please, fill in your contact details in the form below:

First name:
Last name:
Email:
Company:
Address:
City:
Zip code:
Country:
Tel:
Fax:
Your message:

****All fields are required**

Customer signature _____

Please, note that by ordering from marketpublishers.com you are agreeing to our Terms & Conditions at <https://marketpublishers.com/docs/terms.html>

To place an order via fax simply print this form, fill in the information below and fax the completed form to +44 20 7900 3970